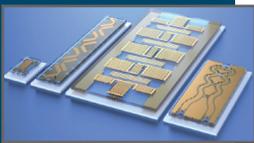
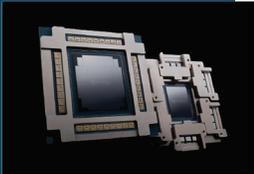


Advanced Packaging Update: Market and Technology Trends

Vol. 2-0725



This issue of the Advanced Packaging Update includes a financial analysis of the top 20 OSATs. A special section is devoted to the demand for large substrates and developments in glass core substrates. Alternatives such as RDL interposers are described. Substrate material shortages are discussed. Thermal interface material needs for large body size packages are analyzed and new developments are included. Substrate design rules are presented for laminate flip chip BGA and CSP substrate suppliers including body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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ACCESS, ASE Materials, AT&S, BRAI, Daeduck, Daisho Denshi, FICT, GS Swiss PCB AG, Haesung, Ibiden, Kinsus, KCC, Kyocera, LG Innotek, Meiko, Nan Ya PCB, R&D Altanova, SEMCO, SCC, Shinko Electric, Simmtech, Toppan, TTM, Unimicron

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